

Multi-Pixel Photon Counter (MPPC) for Detection of Scintillation Spectra of Liquid Argon and Xenon



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HAMAMATSU PHOTONICS K.K.

Solid State Division

Our Motivation for this R&D effort...

- **There remain unexplored frontiers of detecting ultralow levels of light with silicon photodetectors.**
- **One such frontier is the extreme cold of cryogenic physics experiments.**
- **Our goal is to explore this frontier with your help and develop suitable detector technologies for the corresponding physics research and discovery.**
- **We further hope that those technologies shall find other applications in the service of humankind as well.**

Liquefied noble gases in cryogenic physics

- **Dark matter search & Neutrinoless double beta decay**
- Liquid Xenon (LXe)
 - Peak emission wavelength: 175nm
 - **Directly detected by VUV photodetector**
- Liquid Argon (LAr)
 - Peak emission wavelength: 128nm
 - **Directly detected by VUV photodetector or indirectly (after WL-shifter) by UV/blue photodetector (typically ~420 nm)**
- *{Liq. He and liq. Ne are not addressed here...}*

Our Photodetector Solution: The MPPC

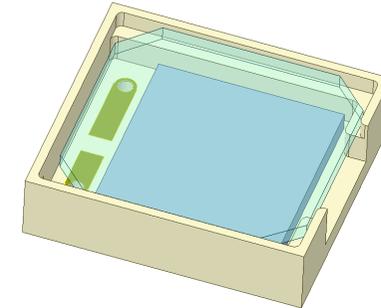
- MPPC Features for Cryogenic Applications
 - Packaging material
 - Cryogenic reliability & radioactivity content
 - Recovery time & temperature characteristics
 - SNR
 - Noise (Cross-talk, After-pulsing, etc.)
 - Gain
 - Photon Detection Efficiency (PDE)

MPPC Packaging: Ultralow RI materials

For direct detection of VUV (128 or 175nm)

Window material: synthetic silica (quartz) for 175nm | none for 125nm

Package material candidates: ceramic, synthetic sapphire, quartz + TGV, intrinsic silicon, etc.



Example: ceramic package + quartz window

For detection of wavelength-shifted 420nm signal

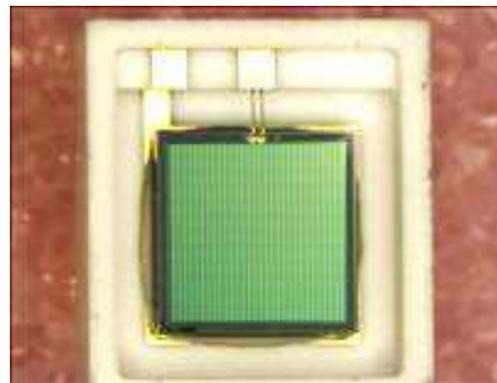
Window material: various kinds of resin

Package material candidates: various kinds of resin



MPPC Packaging: Cryogenic reliability

- **Reliability test on CERAMIC (alumina) PKG w/ quartz window:**
 - Structure : CERAMIC / conductive glue / MPPC / window
 - LN2 \leftrightarrow room temperature, 5cycles
 - 40°C ~ 125°C, 250 cycles
 - 60°C, 90%, 250hr w/ operation (general test)



- **No mechanical or electrical problem!**

MPPC Packaging: Ultralow RI materials

Development strategy

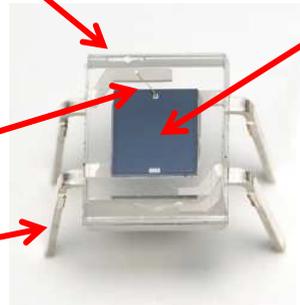
Example: plastic-package device

Molding resin

MPPC chip &
Die bonding resin

Bonding wire

Lead frame



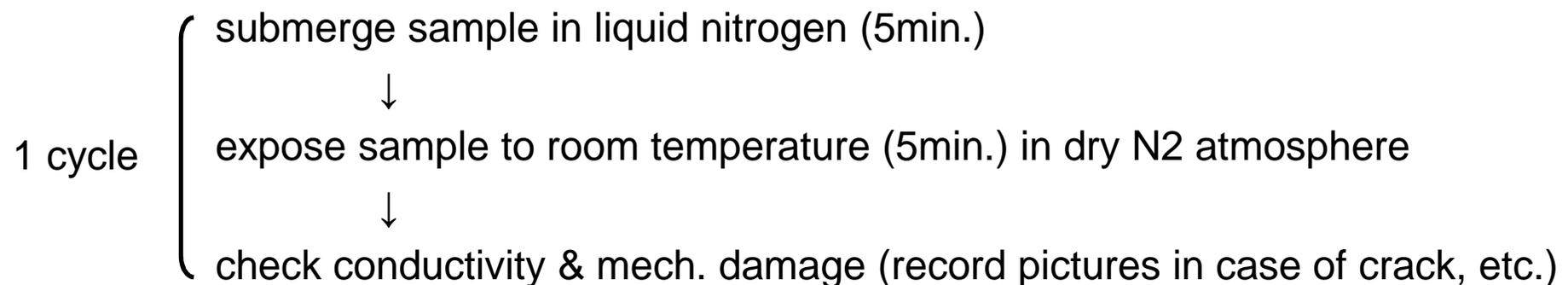
For each component, we have numerous options (different materials and different vendors). We will measure the RI of each component option and identify suitable components for making a low-RI MPPC.

MPPC Packaging: Cryogenic reliability

- **Reliability tests performed on RESIN PKG:**
 - Sample A) Potting: **Epoxy** | Chip mounting: **conductive adhesive glue**
 - Sample B) Potting: **Silicone** | Chip mounting: **conductive adhesive glue**
 - Sample C) Potting: **none (bare)** | Chip mounting: **conductive adhesive glue**
 - Sample D) Potting: **none (bare)** | Chip mounting: **none (fixed by wire bonding)**

Temperature: -196°C (Liquid nitrogen) | **Test cycle:** 20 cycle max.

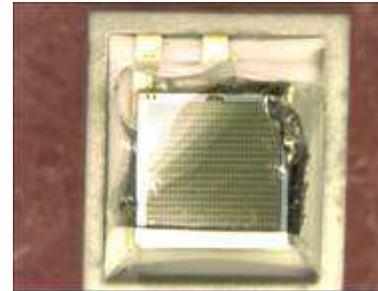
Test Procedure:



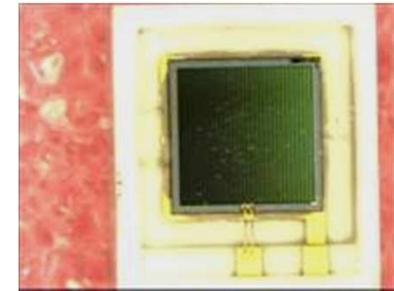
MPPC Packaging: Cryogenic reliability

Results of our reliability tests:

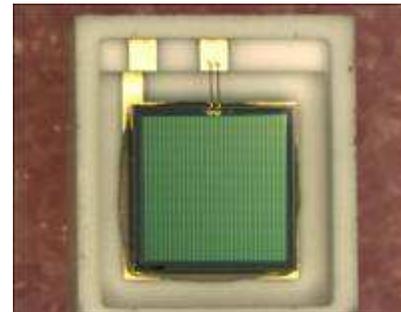
A) **cracked** at 1cycle | 
conductivity: **good** at > 20cycles



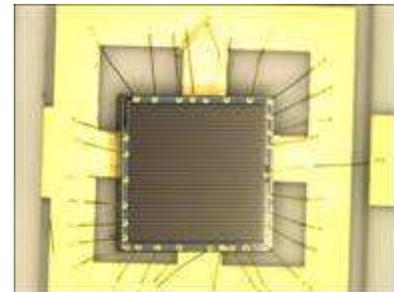
B) **small crack** at 10cycles | 
minor detachment at 20cycles |
conductivity: **good** at > 20cycles



C) **no damage** at >20cycles | 
conductivity: **good** at > 20cycles

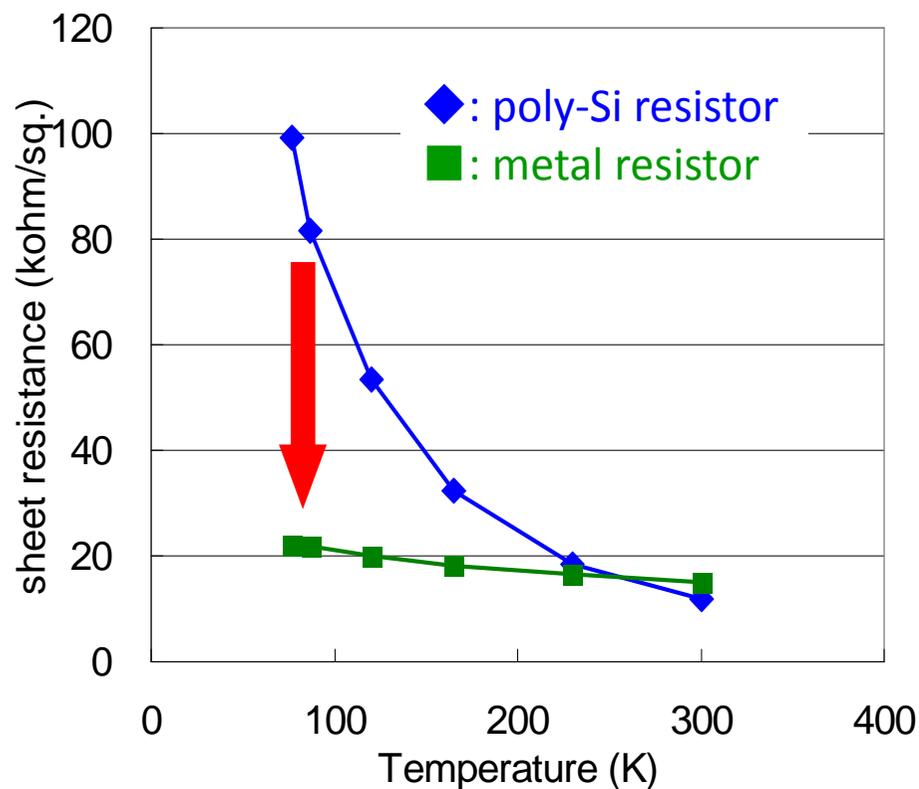


D) **no damage** at >20cycles | 
conductivity: **good** at > 20cycles

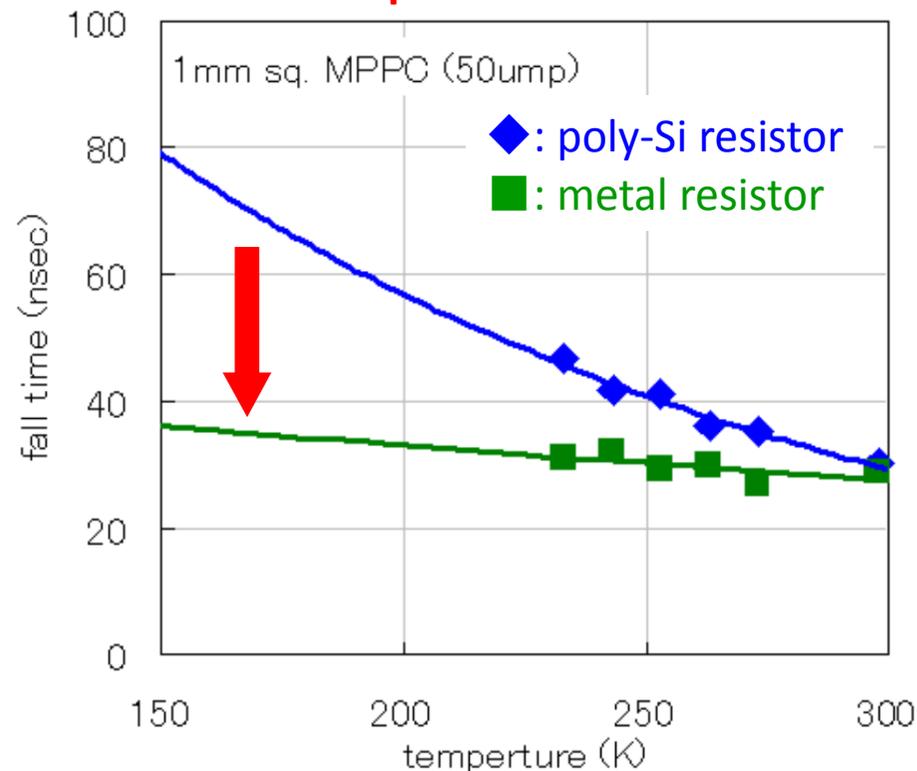


MPPC recovery time at cryogenic temperatures

Temperature dependence of the **sheet resistance**



Temperature dependence of the **pulse fall time**



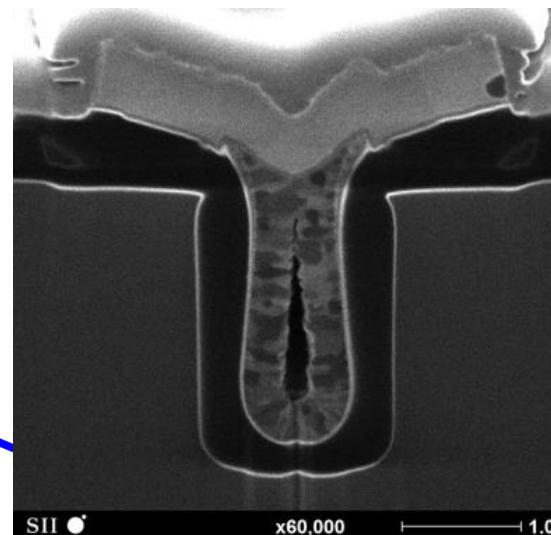
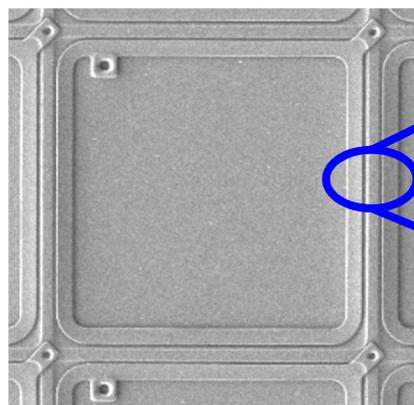
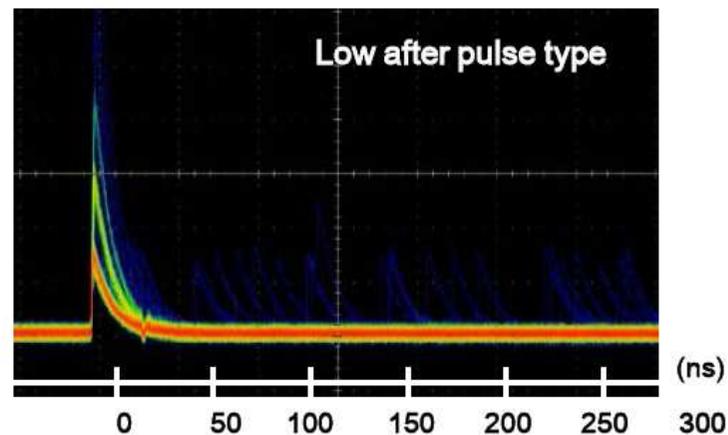
Achieved 1/5th of prior temperature dependence.

For more details, please see:

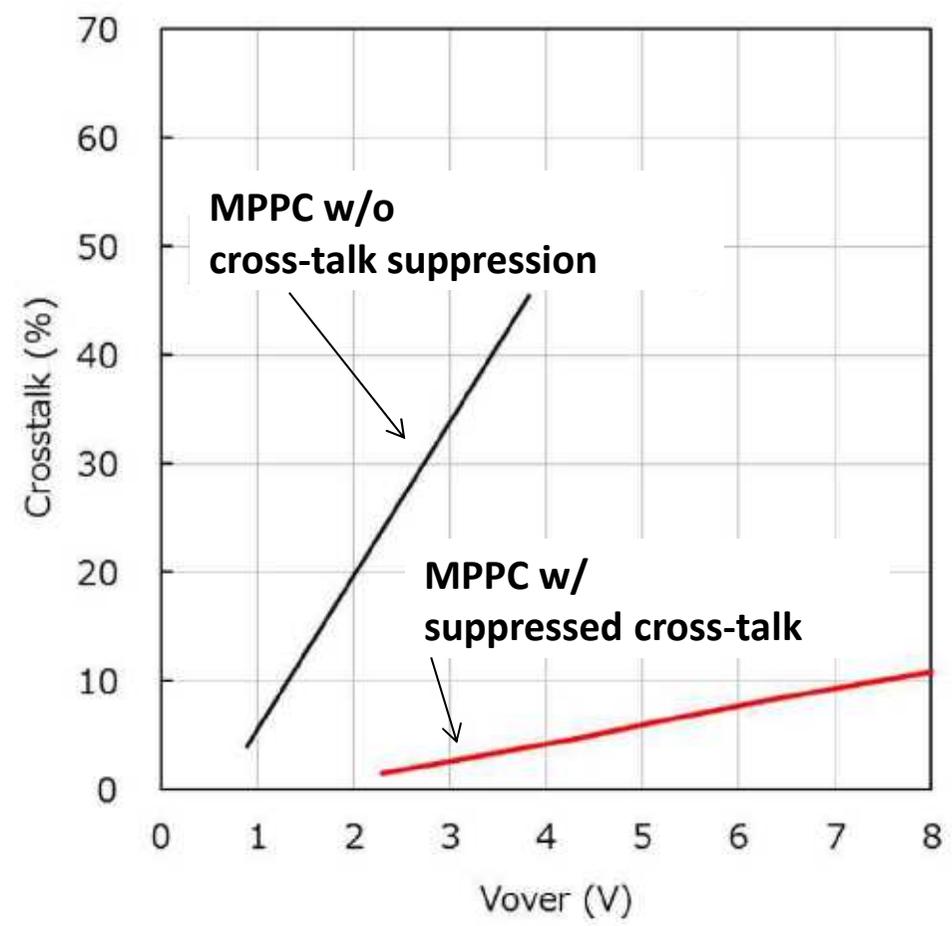
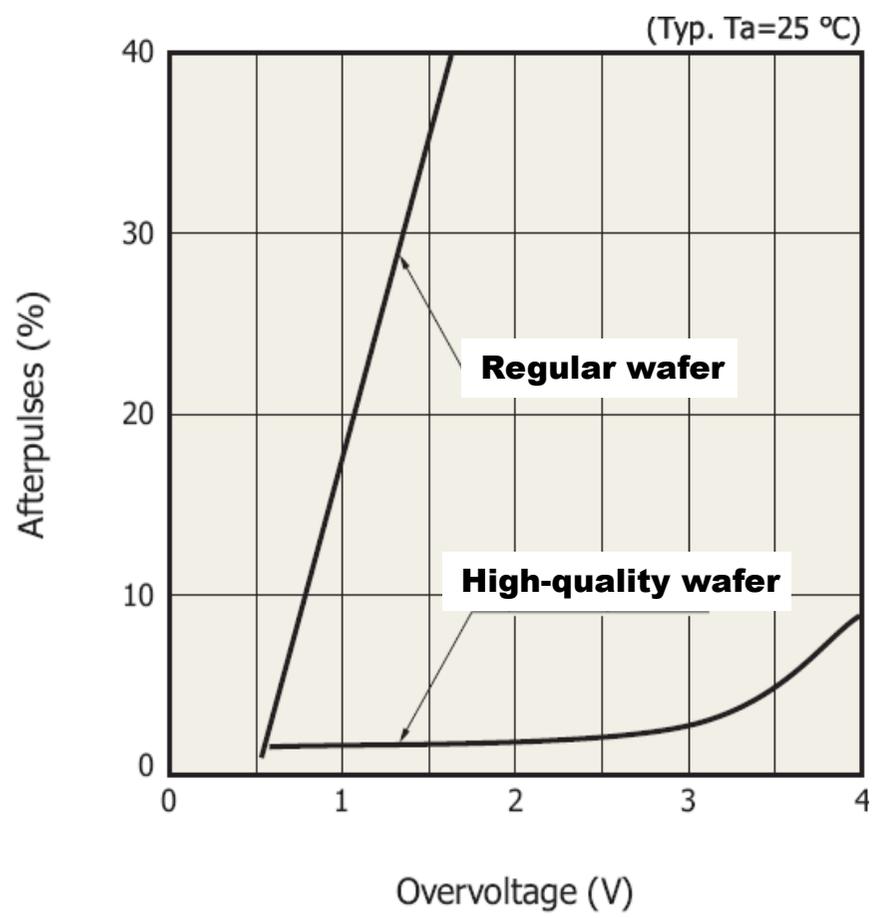
NIM A, Volume 732, Dec. 21, 2013, Pages 427–430, Vienna Conf. on Instrumentation 2013

MPPC Noise (Cross-talk & After-pulsing) Suppression

- After-pulsing suppression
 - Ultralow-defect wafer
- Cross-talk suppression
 - Optical trench around each μ cell

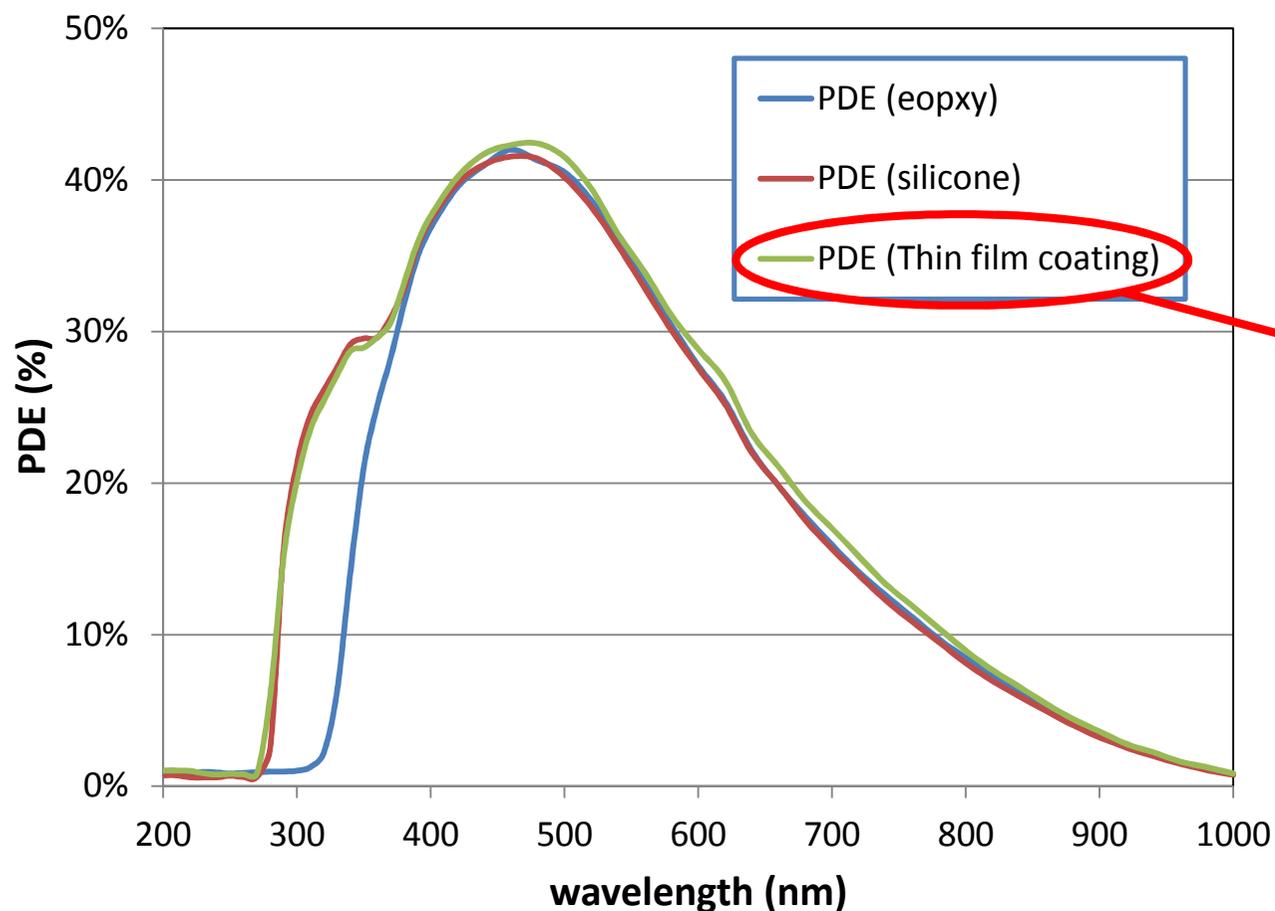


MPPC Noise Suppression



MPPC for detection of 420nm (wavelength-shifted)

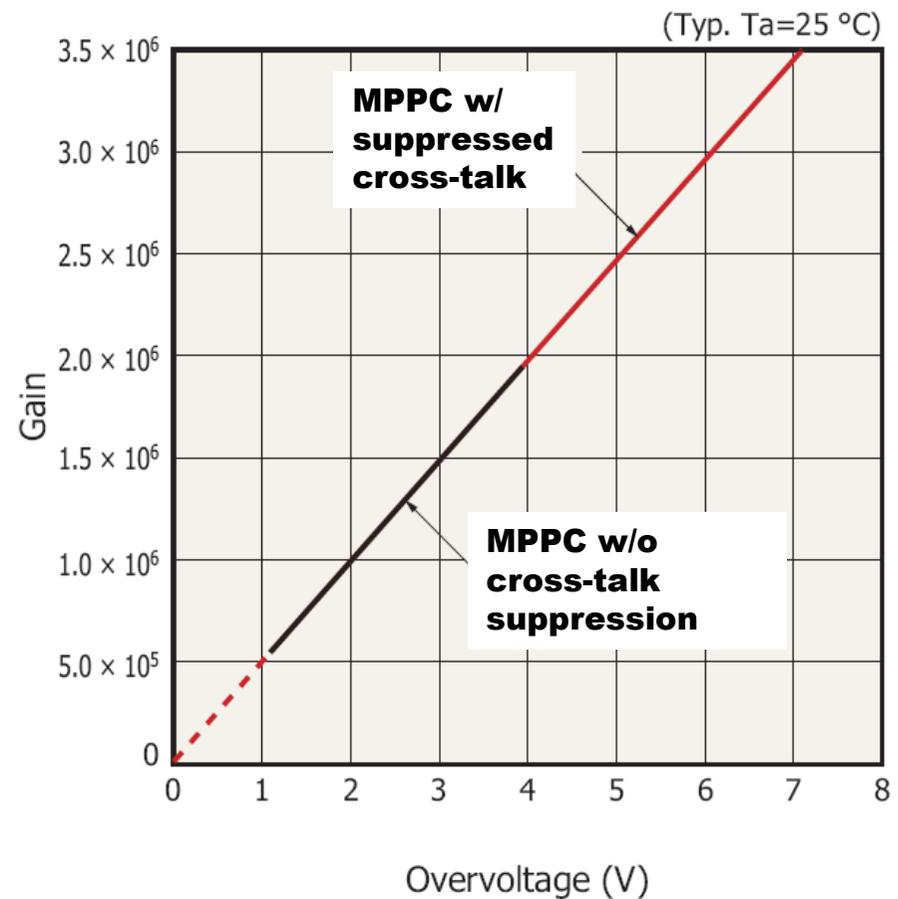
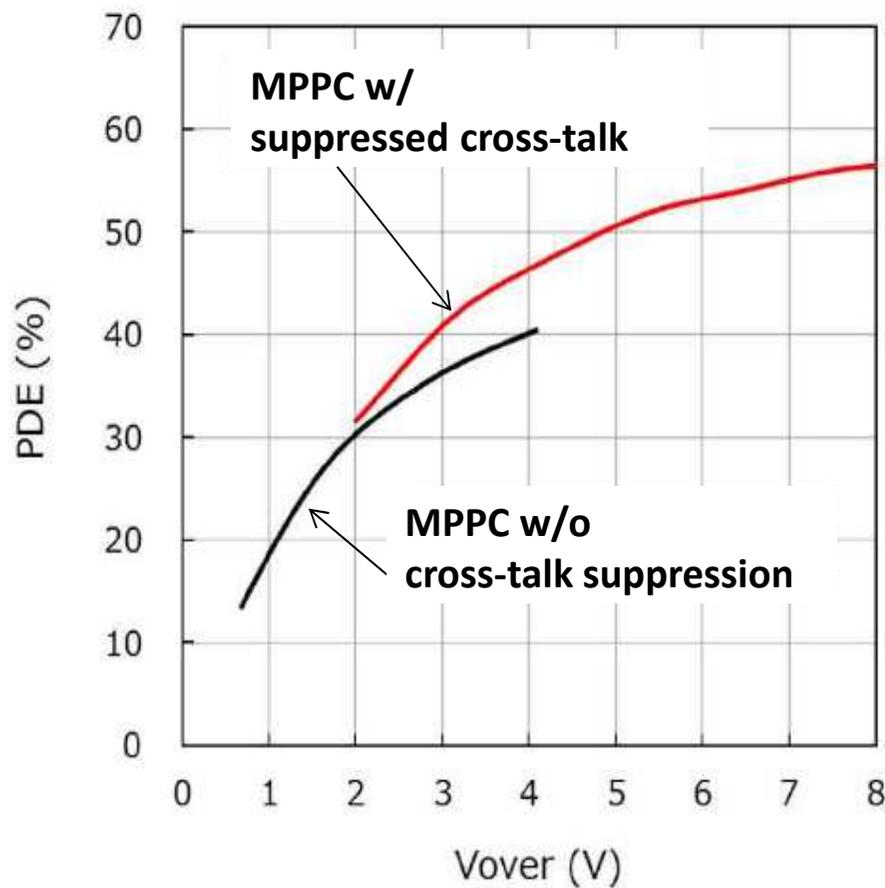
- **MPPC (w/ noise suppression) has remarkable PDE @ 420nm!**
- For comparison with PMT, please note that $PDE = QE \times CE$



For cryogenic operation!

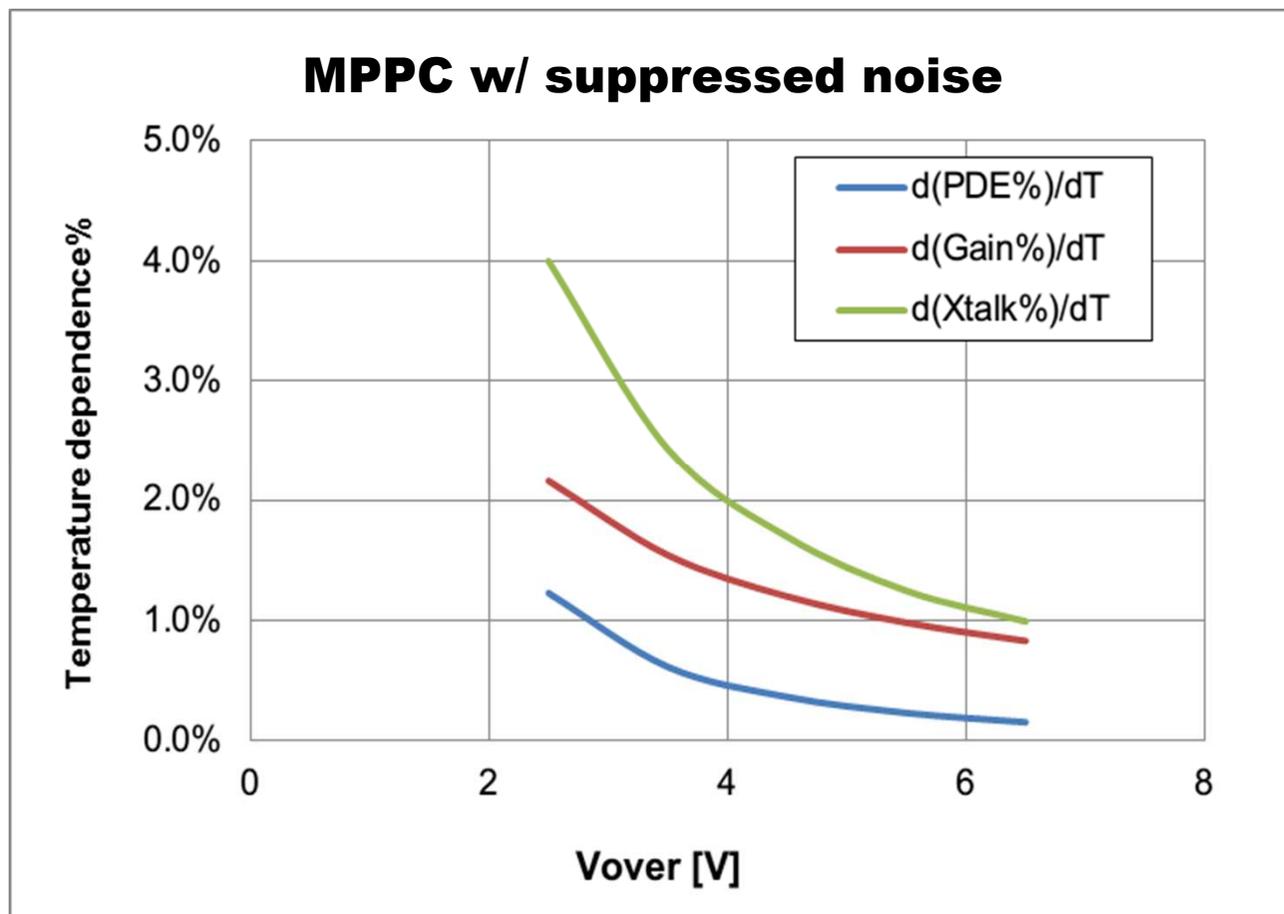
MPPC: Gain & PDE

- Diminished cross-talk allows for higher Over-Voltage (= V bias – V breakdown).
- **Higher OV leads to higher gain and PDE (even compared to last slide).**



Reduced-MPPC Noise: Temperature Stability

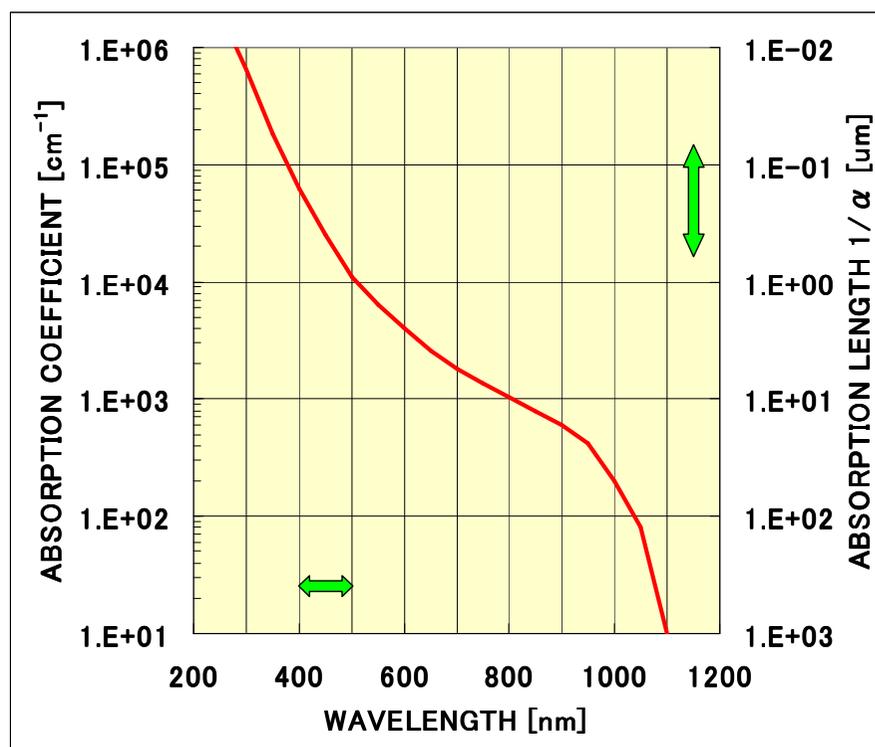
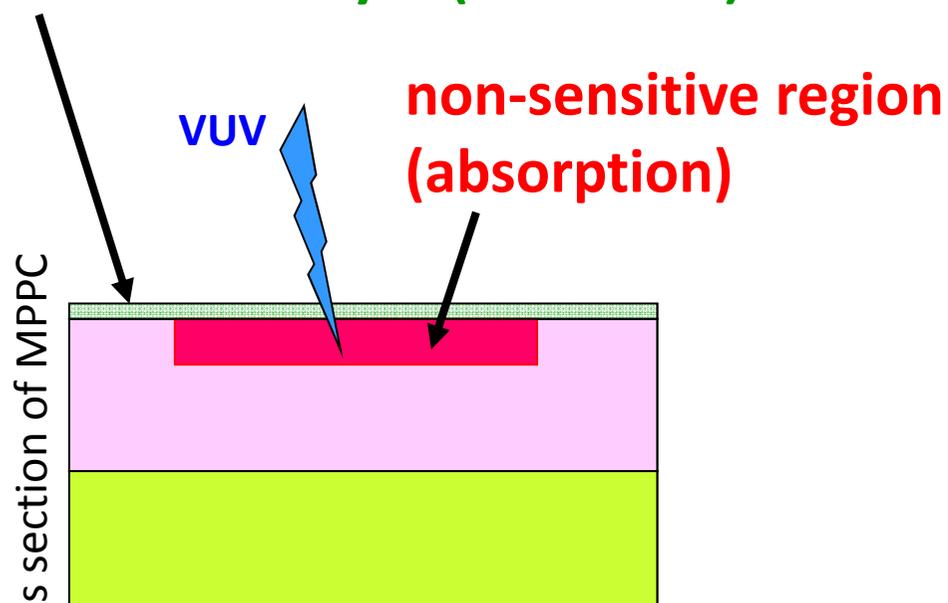
Greater temperature stability is also attained at higher OV.



MPPC's PDE: direct detection of VUV (LAr's 128nm and LXe's 175nm)

- Our solution for direct detection is the “VUV-MPPC” series.

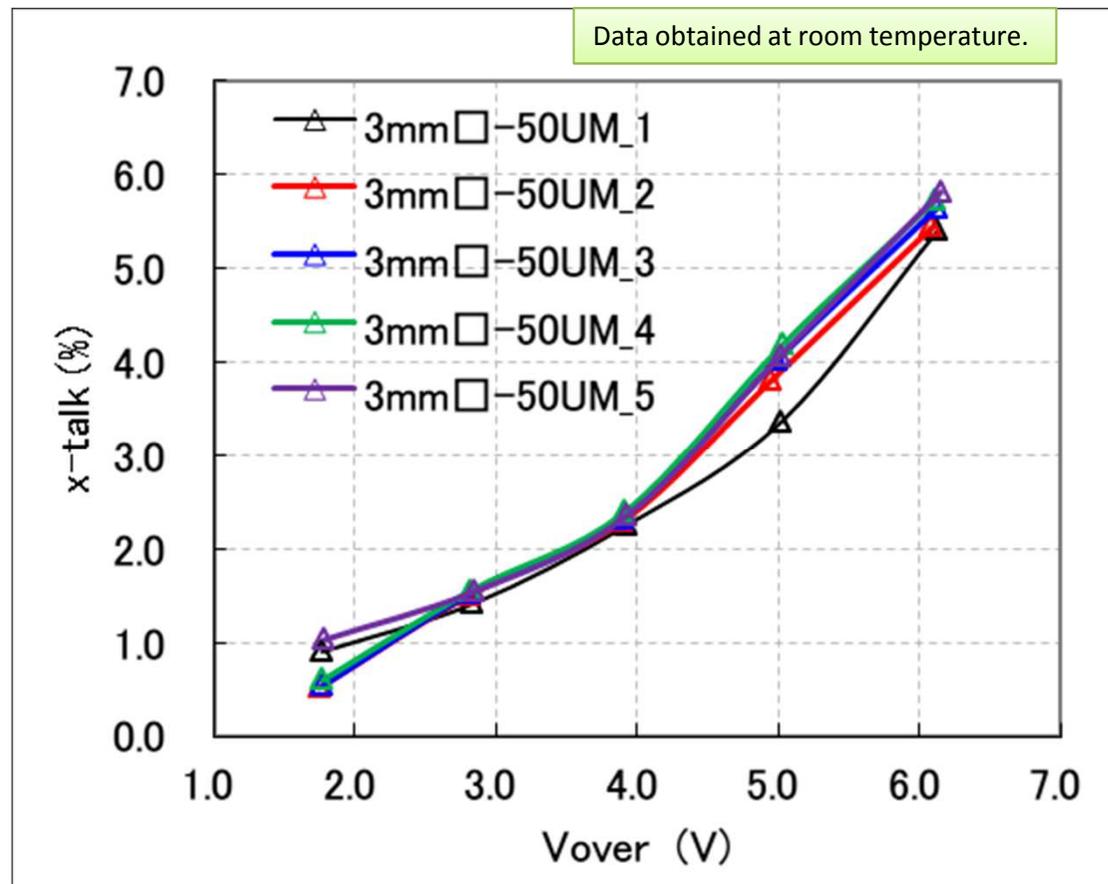
Protection layer (reflection)



For VUV light detection, precise control of MPPC's protection layer and non-sensitive region is required.

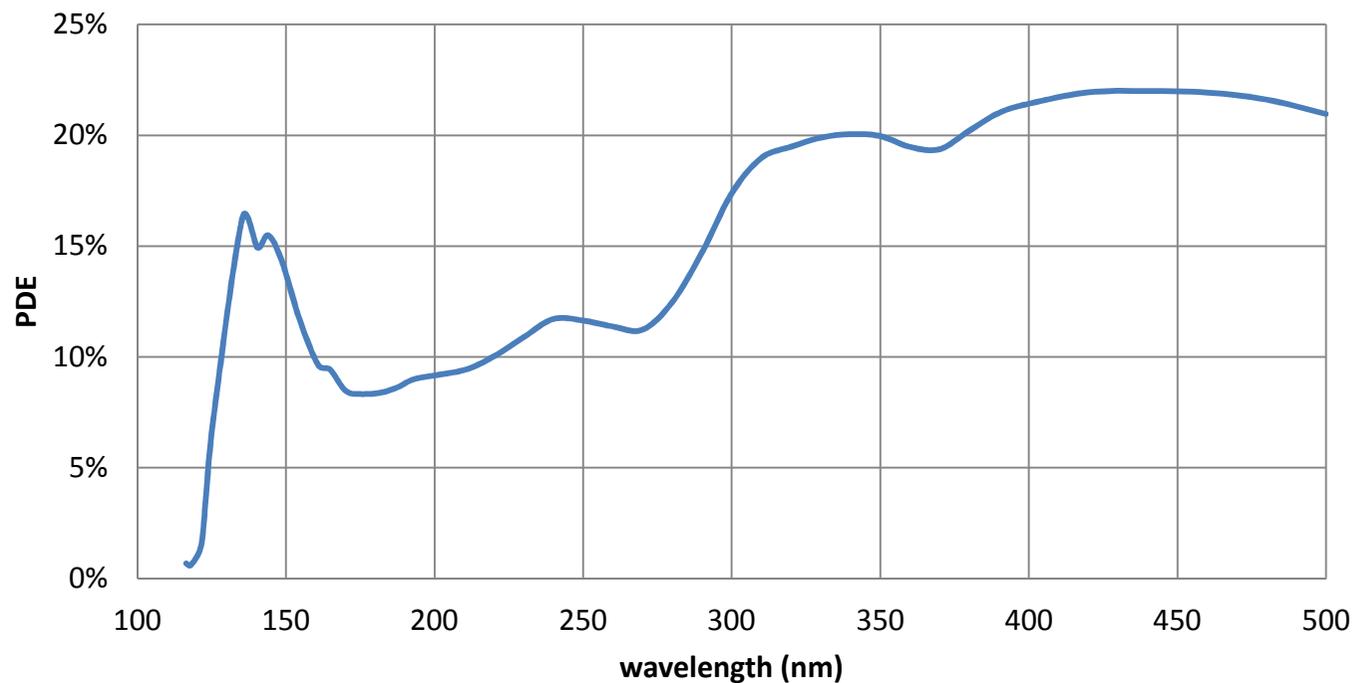
MPPC for direct detection of VUV

- Our latest VUV-MPPC model is VUV3 (w/ optical trenches)



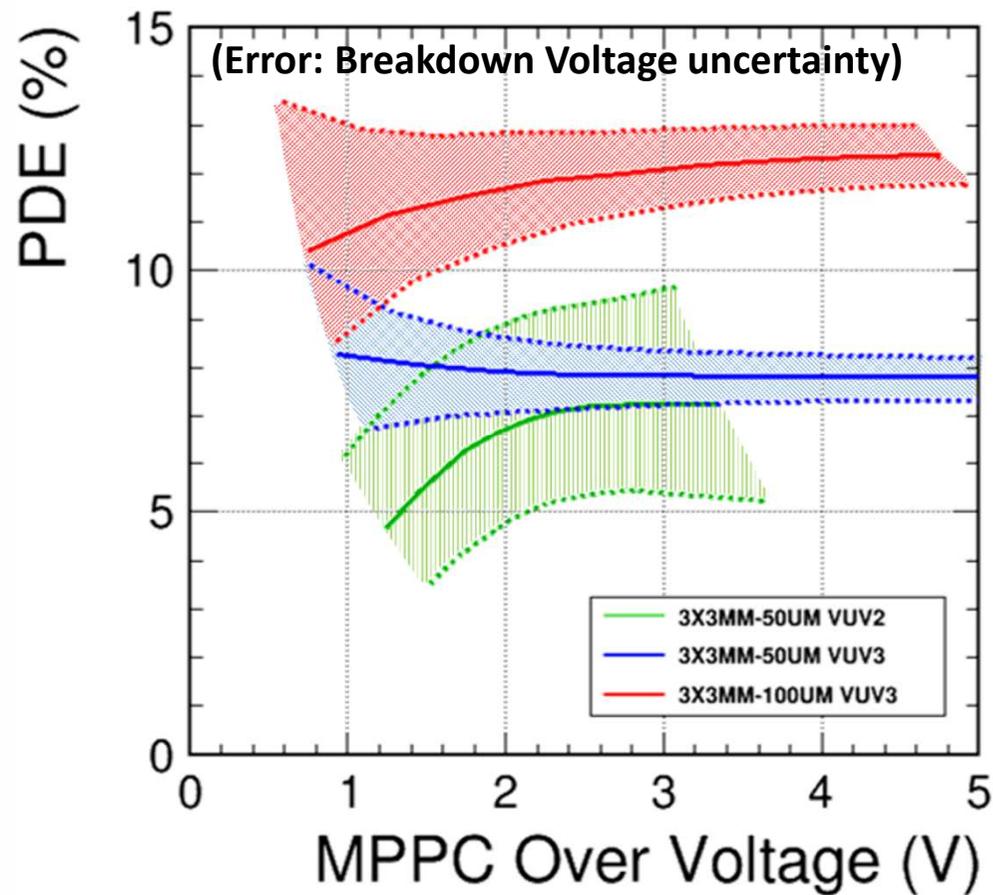
MPPC for direct detection of VUV

PDE of VUV3 MPPC - 3mm chip w/ 50um pixels
Under vacuum <200nm | In Air >200nm | Gain = 1.25×10^6



MPPC for direct detection of VUV

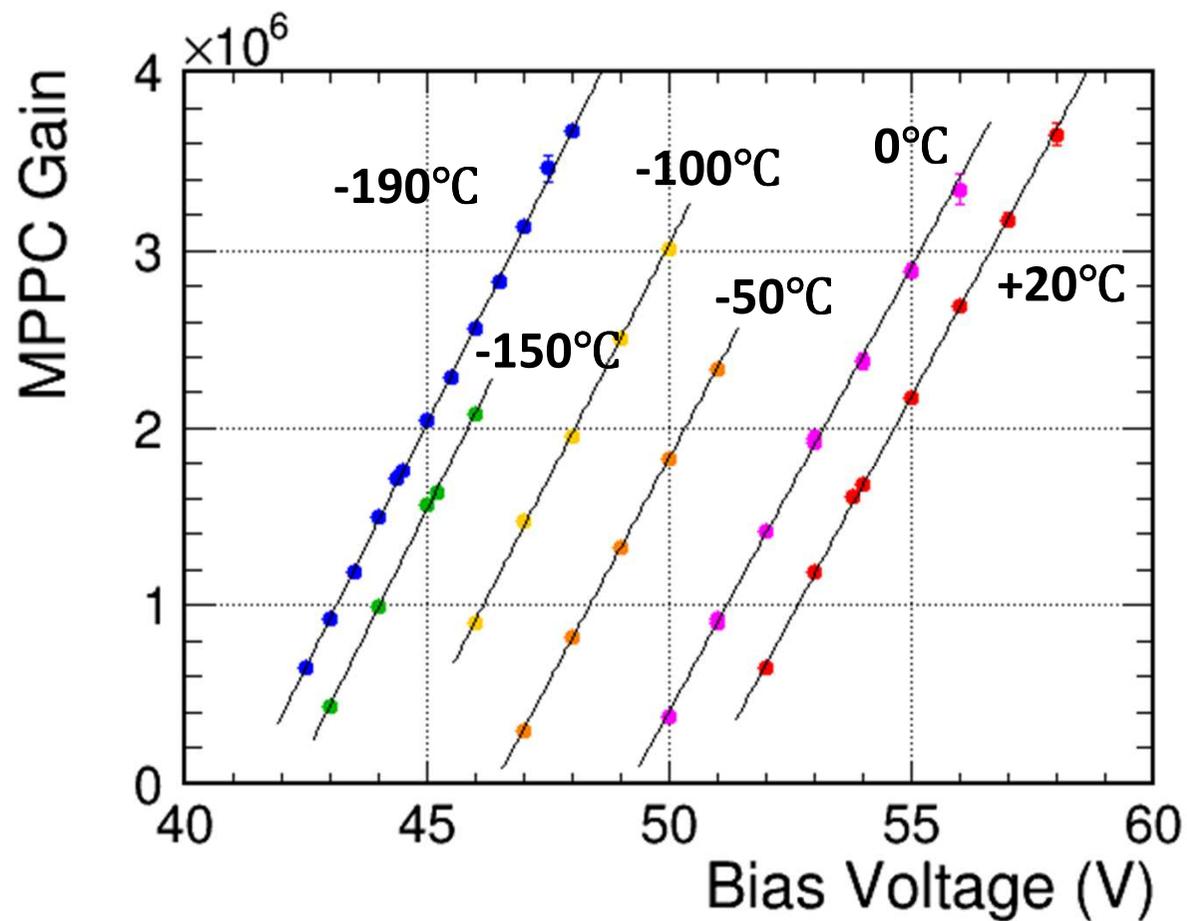
- VUV3's Absolute PDE (LAr emission)



Source: Kohei Yorita, Masashi Tanaka, Tatsuki Washimi of Waseda University, LIDINE 2015 presentation (Albany, NY), August 28, 2015

MPPC for direct detection of VUV

- VUV3's gain characteristics:



Source: Kohei Yorita, Masashi Tanaka, Tatsuki Washimi of Waseda University, LIDINE 2015 presentation (Albany, NY), August 28, 2015

Our near-term development objectives...

- VUV-sensitivity improvement
 - Improvement of pixel fill-factor in VUV-MPPC series
 - Evaluation samples will be available in late 2015 as “VUV4”.

- Lower RI
 - Continuation of radioactivity measurements of various materials for development of an optimal ultralow-RI packaging
 - Evaluation samples will be available in early 2016.

Presentation Summary

- ❑ Overview of Hamamatsu's product development
 - ❑ For cryogenic physics experiments
 - VUV-MPPC
 - Low-RI packaging

- ❑ Communication & Collaboration
 - ❑ We'd love to hear your thoughts regarding current product features along with your ideas for improvements.
 - ❑ We'd also be interested in collaborating with well-equipped researchers on development of ultralow-RI packaging.
 - ❑ So, please feel free to contact us through your local Hamamatsu sales representative.

www.hamamatsu.com